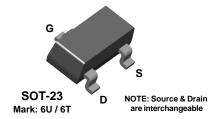


# **J309 J310**

# **MMBFJ309 MMBFJ310**





# **N-Channel RF Amplifier**

This device is designed for VHF/UHF amplifier, oscillator and mixer applications. As a common gate amplifier, 16 dB at 100 MHz and 12 dB at 450 MHz can be realized. Sourced from Process 92.

#### **Absolute Maximum Ratings\*** TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-Source Voltage	25	V
V <sub>GS</sub>	Gate-Source Voltage	- 25	V
I <sub>GF</sub>	Forward Gate Current	10	mA
T <sub>J</sub> ,T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

#### **Thermal Characteristics** TA = 25°C unless otherwise noted

Symbol	Characteristic	Max		Units
		J309-J310	*MMBFJ309-310	
$P_D$	Total Device Dissipation Derate above 25°C	625 5.0	350 2.8	mW mW/∘C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	556	°C/W

<sup>\*</sup>Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06."

<sup>1)</sup> These ratings are based on a maximum junction temperature of 150 degrees C.

2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

# N-Channel RF Amplifier (continued)

Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
OFF CHA	RACTERISTICS						
V <sub>(BR)GSS</sub>	Gate-Source Breakdown Voltage	$I_G = -1.0  \mu A,  V_{DS} = 0$		- 25			V
I <sub>GSS</sub>	Gate Reverse Current	V <sub>GS</sub> = - 15 V, V <sub>DS</sub> = 0 V <sub>GS</sub> = - 15 V, V <sub>DS</sub> = 0, T <sub>A</sub> = 125°C				- 1.0 - 1.0	nA μA
V <sub>GS(off)</sub>	Gate-Source Cutoff Voltage	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1.0 nA	309 310	- 1.0 - 2.0		- 4.0 - 6.5	V V
ON CHAR	RACTERISTICS  Zero-Gate Voltage Drain Current*	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0	309 310	12 24		30 60	mA mA
	Current	$V_{DS} = 0$ , $I_{G} = 1.0$ mA	310	24		1.0	V

#### SMALL SIGNAL CHARACTERISTICS

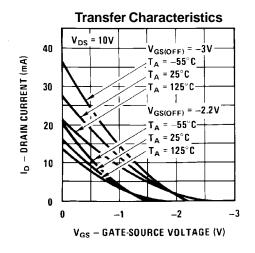
Re <sub>(yis)</sub>	Common-Source Input	$V_{DS} = 10$ , $I_{D} = 10$ mA, $f = 100$ MHz				
(5 -)	Conductance	309		0.7		mmhos
		310		0.5		mmhos
Re <sub>(</sub> y <sub>os)</sub>	Common-Source Output Conductance	$V_{DS} = 10$ , $I_D = 10$ mA, $f = 100$ MHz		0.25		mmhos
G <sub>pg</sub>	Common-Gate Power Gain	$V_{DS} = 10$ , $I_D = 10$ mA, $f = 100$ MHz		16		dB
Re <sub>(</sub> y <sub>fs)</sub>	Common-Source Forward Transconductance	$V_{DS} = 10$ , $I_D = 10$ mA, $f = 100$ MHz		12		mmhos
Re <sub>(</sub> y <sub>ig)</sub>	Common-Gate Input Conductance	$V_{DS} = 10$ , $I_{D} = 10$ mA, $f = 100$ MHz		12		mmhos
9fs	Common-Source Forward	$V_{DS} = 10$ , $I_{D} = 10$ mA, $f = 1.0$ kHz				
_	Transconductance	309	10,000		20,000	μmhos
		310	8000		18,000	μmhos
goss	Common-Source Output Conductance	$V_{DS} = 10$ , $I_{D} = 10$ mA, $f = 1.0$ kHz			150	μmhos
<b>g</b> fg	Common-Gate Forward	$V_{DS} = 10$ , $I_{D} = 10$ mA, $f = 1.0$ kHz				
	Conductance	309		13,000		μmhos
		310		12,000		μmhos
gog	Common-Gate Output	$V_{DS} = 10$ , $I_{D} = 10$ mA, $f = 1.0$ kHz				
- •	Conductance	309		100		μmhos
		310		150		μmhos
C <sub>dg</sub>	Drain-Gate Capacitance	$V_{DS} = 0$ , $V_{GS} = -10 \text{ V}$ , $f = 1.0 \text{ MHz}$		2.0	2.5	pF
C <sub>sg</sub>	Source-Gate Capacitance	$V_{DS} = 0$ , $V_{GS} = -10 \text{ V}$ , $f = 1.0 \text{ MHz}$		4.1	5.0	pF
NF	Noise Figure	$V_{DS} = 10 \text{ V}, I_{D} = 10 \text{ mA},$ f = 450 MHz		3.0		dB
en	Equivalent Short-Circuit Input Noise Voltage	$V_{DS} = 10 \text{ V}, I_{D} = 10 \text{ mA},$ f = 100 Hz		6.0		nV/√Hz

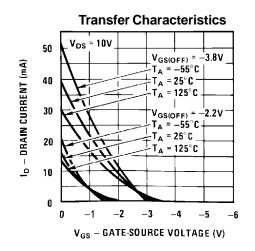
<sup>\*</sup>Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%

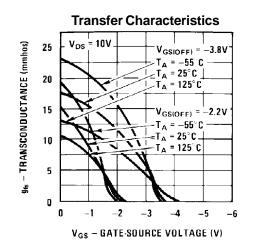
#### **N-Channel RF Amplifier**

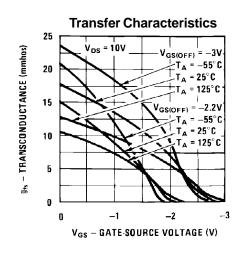
(continued)

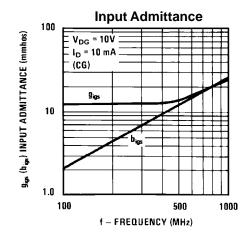
# **Typical Characteristics**

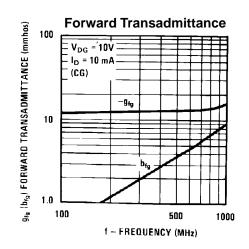








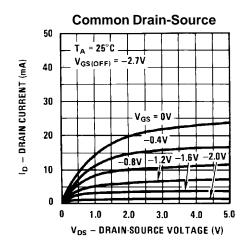


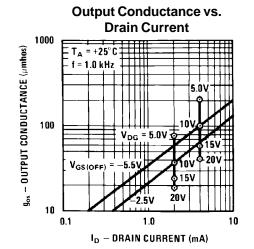


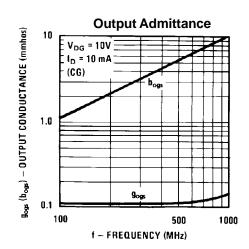
# **N-Channel RF Amplifier**

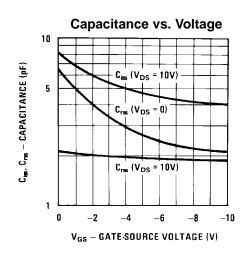
(continued)

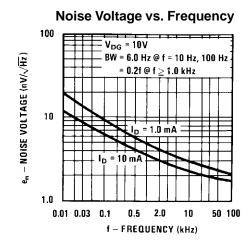
# Typical Characteristics (continued)

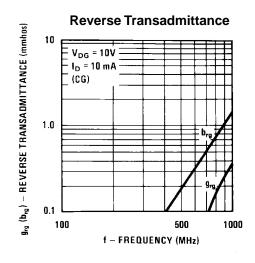








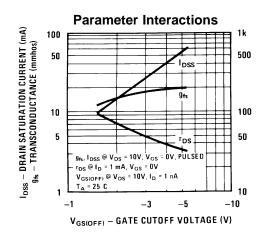


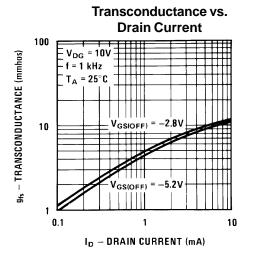


# **N-Channel RF Amplifier**

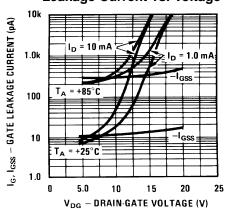
(continued)

# Typical Characteristics (continued)

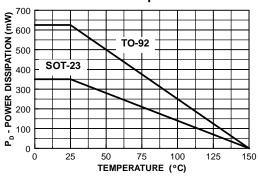




#### Leakage Current vs. Voltage



#### Power Dissipation vs Ambient Temperature



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